SNOS552D - MAY 1998 - REVISED APRIL 2013

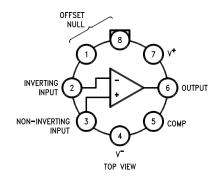
## **LM725 Operational Amplifier**

Check for Samples: LM725

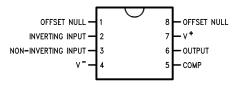
### **FEATURES**

- High Open Loop Gain: 3,000,000
- Low Input Voltage Drift 0.6 μV/°C
- High Common Mode Rejection 120 dB
- Low Input Noise Current 0.15 pA/√Hz
- Low Input Offset Current 2 nA
- High Input Voltage Range ±14V
- Wide Power Supply Range ±3V to ±22V
- Offset Null Capability
- Output Short Circuit Protection

### **CONNECTION DIAGRAM**



Metal Can Package



**Dual-In-Line Package** 

### DESCRIPTION

The LM725/LM725A/LM725C are operational amplifiers featuring superior performance in applications where low noise, low drift, and accurate closed-loop gain are required. With high common mode rejection and offset null capability, it is especially suited for low level instrumentation applications over a wide supply voltage range.

The LM725A has tightened electrical performance with higher input accuracy and like the LM725, is guaranteed over a -55°C to +125°C temperature range. The LM725C has slightly relaxed specifications and has its performance guaranteed over a 0°C to 70°C temperature range.

#### TYPICAL APPLICATIONS

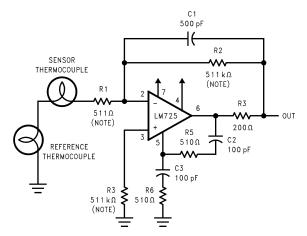


Figure 1. Thermocouple Amplifier

A

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### **ABSOLUTE MAXIMUM RATINGS (1)**

If Military/Aerospace specified devices are required, contact the Texas Instruments Semiconductor Sales Office/ Distributors for availability and specifications. (2)

Supply Voltage	±22V
Internal Power Dissipation (3)	500 mW
Differential Input Voltage	±5V
Input Voltage (4)	±22V
Storage Temperature Range	−65°C to +150°C
Lead Temperature (Soldering, 10 Sec.)	260°C
Maximum Junction Temperature	150°C
Operating Temperature Range (T <sub>A(MIN)</sub> to T <sub>A(MAX)</sub> )	
LM725	−55°C to +125°C
LM725A	−55°C to +125°C
LM725C	0°C to +70°C

<sup>(1) &</sup>quot;Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but **do not** guarantee specific performance limits.

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<sup>(2)</sup> For Military electrical specifications RETS725AX are available for LM725AH and RETS725X are available for LM725H.

<sup>(3)</sup> Derate at 150°C/W for operation at ambient temperatures above 75°C.

<sup>(4)</sup> For supply voltages less than ±22V, the absolute maximum input voltage is equal to the supply voltage.

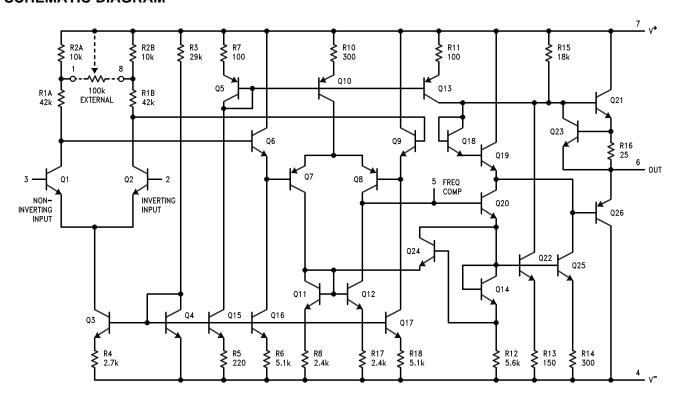
### **ELECTRICAL CHARACTERISTICS (1)**

		LM725A				LM725			LM725C		
Parameter	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Units
Input Offset Voltage (Without External Trim)	$T_A = 25^{\circ}C$ , $R_S \le 10 \text{ k}\Omega$			0.5		0.5	1.0		0.5	2.5	mV
Input Offset Current	T <sub>A</sub> = 25°C		2.0	5.0		2.0	20		2.0	35	nA
nput Bias Current	T <sub>A</sub> = 25°C		42	80		42	100		42	125	nA
nput Noise Voltage	T <sub>A</sub> = 25°C										
	$f_o = 10 \text{ Hz}$		15			15			15		nV/√Hz
	f <sub>o</sub> = 100 Hz		9.0			9.0			9.0		nV/√Hz
	f <sub>o</sub> = 1 kHz		8.0			8.0			8.0		nV/√Hz
Input Noise Current	$T_A = 25^{\circ}C$										
	$f_o = 10 \text{ Hz}$		1.0			1.0			1.0		pA/√Hz
	f <sub>o</sub> = 100 Hz		0.3			0.3			0.3		pA/√ <del>Hz</del>
	$f_o = 1 \text{ kHz}$		0.15			0.15			0.15		pA/√ <del>Hz</del>
Input Resistance	T <sub>A</sub> = 25°C		1.5			1.5			1.5		ΜΩ
Input Voltage Range	T <sub>A</sub> = 25°C	±13.5	±14		±13.5	±14		±13.5	±14		V
Large Signal Voltage Gain	$T_A = 25^{\circ}C,$ $R_L \ge 2 \text{ k}\Omega,$ $V_{OUT} = \pm 10\text{V}$	1000	3000		1000	3000		250	3000		V/mV
Common-Mode Rejection Ratio	$T_A = 25^{\circ}C$ , $R_S \le 10 \text{ k}\Omega$	120			110	120		94	120		dB
Power Supply Rejection Ratio	$T_A = 25^{\circ}C$ , $R_S \le 10 \text{ k}\Omega$		2.0	5.0		2.0	10		2.0	35	μV/V
Output Voltage Swing	$T_A = 25$ °C,										
	$R_L \ge 10 \text{ k}\Omega$	±12.5	±13.5		±12	±13.5		±12	±13.5		V
	$R_L \ge 2 k\Omega$	±12.0	±13.5		±10	±13.5		±10	±13.5		V
Power Consumption	T <sub>A</sub> = 25°C		80	105		80	105		80	150	mW
Input Offset Voltage (Without External Trim)	R <sub>S</sub> ≤ 10 kΩ			0.7			1.5			3.5	mV
Average Input Offset Voltage Drift (Without External Trim)	$R_S = 50\Omega$			2.0		2.0	5.0		2.0		μV/°C
Average Input Offset Voltage Drift (With External Trim)	$R_S = 50\Omega$		0.6	1.0		0.6			0.6		μV/°C
Input Offset Current	$T_A = T_{MAX}$		1.2	4.0		1.2	20		1.2	35	nA
	$T_A = T_{MIN}$		7.5	18.0		7.5	40		4.0	50	nA
Average Input Offset Current Drift			35	90		35	150		10		pA/°C
Input Bias Current	$T_A = T_{MAX}$		20	70		20	100			125	nA
	$T_A = T_{MIN}$		80	180		80	200			250	nA
Large Signal Voltage	R <sub>L</sub> ≥ 2 kΩ										
Gain	$T_A = T_{MAX}$	1,000,000			1,000,000			125,000			V/V
	$R_L \ge 2 k\Omega$										
	$T_A = T_{MIN}$	500,000			250,000			125,000			V/V
Common-Mode Rejection Ratio	R <sub>S</sub> ≤ 10 kΩ	110			100				115		dB
Power Supply Rejection Ratio	R <sub>S</sub> ≤ 10 kΩ			8.0			20		20		μV/V
Output Voltage Swing	R <sub>L</sub> ≥ 2 kΩ	±12		1	±10			±10	-		V

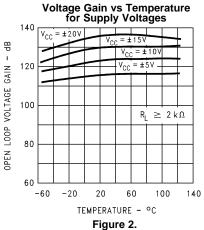
<sup>(1)</sup> These specifications apply for  $V_S = \pm 15V$  unless otherwise specified.



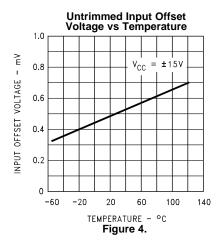
### **SCHEMATIC DIAGRAM**

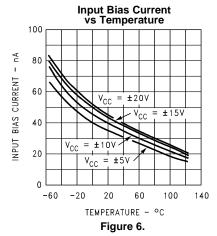


#### TYPICAL PERFORMANCE CHARACTERISTICS

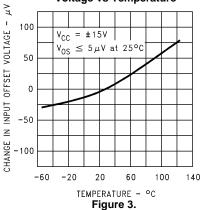




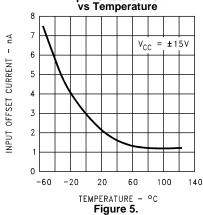




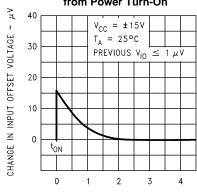
# Change in Trimmed Input Offset Voltage vs Temperature



**Input Offset Current** 



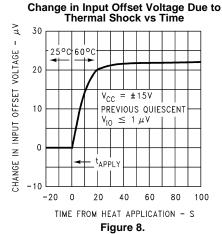
# Stabilization Time of Input Offset Voltage from Power Turn-On



TIME FROM POWER APPLICATION - MIN Figure 7.



### TYPICAL PERFORMANCE CHARACTERISTICS (continued)



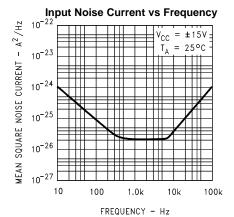
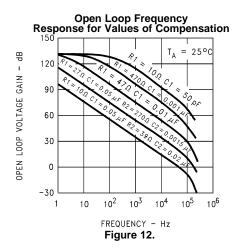
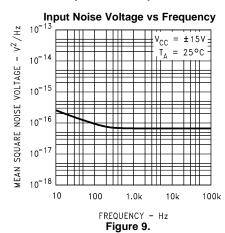
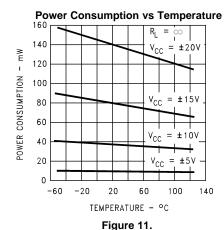


Figure 10.







### **Values for Suggested Compensation Networks**

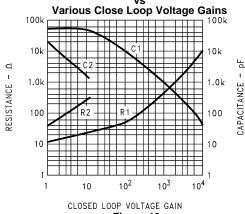
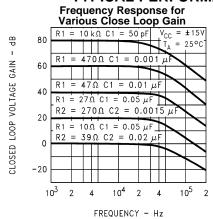


Figure 13.

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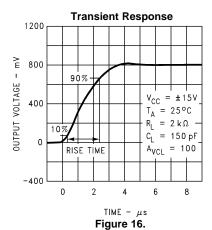
### TYPICAL PERFORMANCE CHARACTERISTICS (continued)



- (1) Performance is shown using recommended compensation networks.
- (1) Performance is shown using recommended compensation networks.

Figure 15.

Figure 14.



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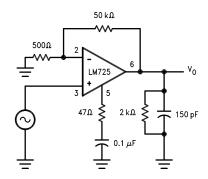


Figure 17. Transient Response Test Circuit

### **AUXILIARY CIRCUITS**

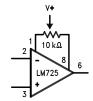


Figure 18. Voltage Offset Null Circuit

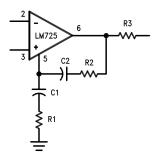


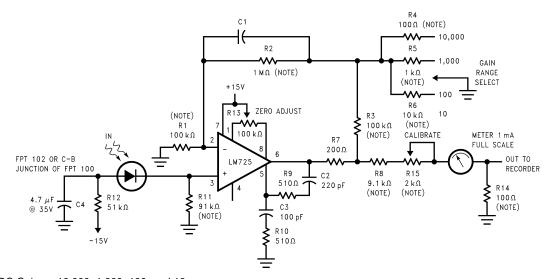
Figure 19. Frequency Compensation Circuit

**Table 1. Compensation Component Values** 

A <sub>V</sub>	R <sub>1</sub> (Ω)	C <sub>1</sub> (μF)	R <sub>2</sub> (Ω)	C <sub>2</sub> (μF)
10,000	10k	50 pF		
1,000	470	0.001		
100	47	0.01		
10	27	0.05	270	0.0015
1	10	0.05	39	0.02

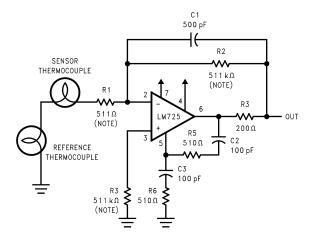
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### TYPICAL APPLICATIONS



DC Gains = 10,000; 1,000; 100; and 10 Bandwidth = Determined by value of C1

Figure 20. Photodiode Amplifier



```
\begin{split} \frac{R2}{R5} &= \frac{R6}{R7} \text{ for best CMR} \\ R1 &= R4 \\ R2 &= R5 \\ Gain &= \frac{R6}{R2} + \left(\frac{2R1}{R3}\right) \\ DC \ Gain &= 1000 \\ Bandwidth &= DC \ to 540 \ Hz \\ Equivalent Input Noise &= 0.24 \ \mu\text{V}_{rms} \end{split}
```

Indicates  $\pm 1\%$  metal film resistors recommended for temperature stability.

Figure 21. Thermocouple Amplifier



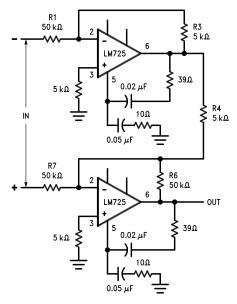
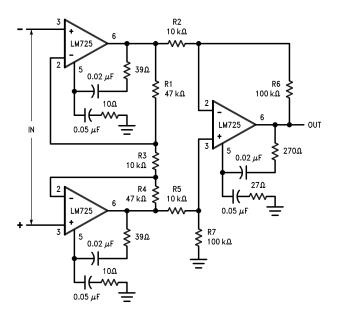


Figure 22. ±100V Common Mode Range Differential Amplifier



```
\frac{R1}{R6} = \frac{R3}{R4} \text{ for best CMRR}
R3 = R4
R1 = R6 = 10 R3
Gain = \frac{R6}{R7}
```

Figure 23. Instrumentation Amplifier with High Common Mode Rejection

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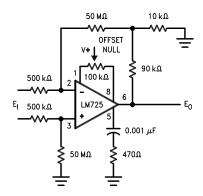


Figure 24. Precision Amplifier  $A_{VCL} = 1000$ 

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### **REVISION HISTORY**

Changes from Revision C (April 2013) to Revision D			
•	Changed layout of National Data Sheet to TI format		11

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